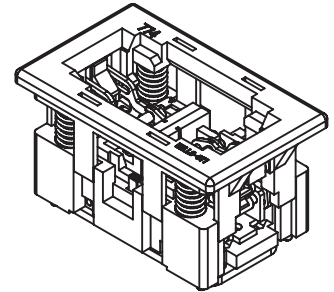
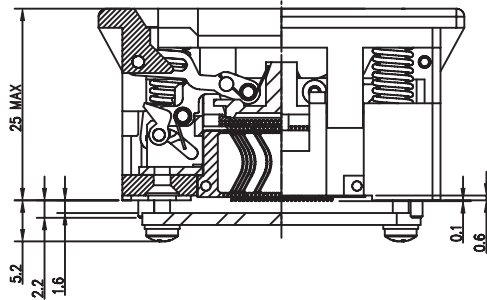
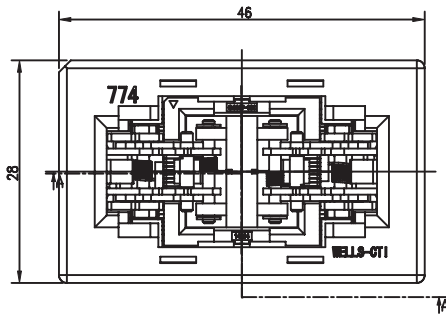
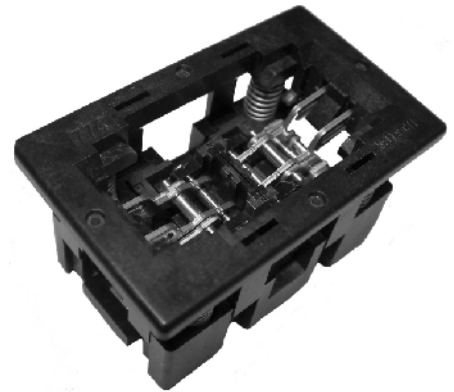




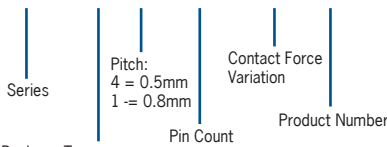
774 SERIES OPEN TOP CSP

- 0.5mm and 0.8mm pitch
- Compression surface mount
- High performance/low cost achieved through use of carrier loaded stamped contact
- Z-axis compliant buckling beam contact provides stable contact performance independent of solder ball height and composition
- Advanced latch mechanism with flexible pressure pads provides uniformed force distribution across the package surface, enabling the socket to handle up to 900 balls (full 30x30 matrix) and super thin packages



DESCRIPTION & ORDERING INFORMATION

774 X X XXX - X XX



Package Type:
 C = 0.5mm pitch U contact
 K = 0.5mm pitch LGA contact
 P = 0.5mm pitch QFN contact
 N = 0.8mm pitch U contact

MATERIALS & SPECIFICATIONS

- Body Materials: PES, PEI, LCP or Equivalent
- Contact Material: Beryllium Copper Alloy
- Contact Plating: Gold
- Contact Force: 13 gram average
- Contact Resistance: 200~300 mΩ
- Temperature Rating: 150°C
- Durability: 10,000 cycles min.

Pitch e (mm)	Package Size (mm)	Pin Matrix.	Max. Pin Count	Ball Dia. (mm)	Ball Height (mm)	Part Number
0.5	13X10	25X19	475	0.32	0.23	774C4475-XXX
	12X12	23X23	529	0.30	0.21	774C4529-XXX
	15X10	28X19	532	0.30	0.25	774C4532-XXX
	14X14	25X25	625	0.30	0.21	774C4625-XXX
	14X14	26X26	676	0.30	0.20	774C4676-XXX
	14X14	27X27	729	0.30	0.24	774C4729-XXX
	15X15	29X29	841	0.32	0.24	774C4841-XXX
0.8	15X15	17X17	289	0.30	0.15	774N1289-XXX